

# 曜凌光電股份有限公司

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### **RX12864B-FHW**

### **SPECIFICATION**

### **CUSTOMER:**

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:



# **Revision History**

VERSION	DATE	REVISED PAGE NO.	Note
0	2012/09/03		First issue
Α	2014/07/22		Remove IC
			information
В	2016/02/25		Modify Precautions in
			use of LCD Modules
			& Static electricity
			test
C	2016/11/24		Add FPC bending
			rule



## **Contents**

- 1. General Specification
- 2. Module Classification Information
- 3.Interface Pin Function
- 4. Contour Drawing & Block Diagram
- 5. Optical Characteristics
- 6. Absolute Maximum Ratings
- 7. Electrical Characteristics
- 8.Backlight Information
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of LCD Modules
- 12. Material List of Components for RoHs
- 13.Recommendable Storage



## 1.General Specification

The Features is described as follow:

■ Module dimension: 89.7x 49.8 x12.1 (max.) mm

■ View area: 69.0 x 36.5 mm

Active area: 63.97 x31.97 mm

■ Number of dots: 128 x 64

■ Dot size: 0.47 x0.47 mm

■ Dot pitch: 0.5 x 0.5 mm

■ LCD type: FSTN Positive Transflective

■ Duty: 1/65 , 1/9 Bias

■ View direction: 6 o'clock

■ Backlight Type: LED, White

■ IC: ST7565P



### 2. Module Classification Information

<u>R</u>	<u>X</u>	<u>12864</u>	<u>B</u>	_	<u>F</u>	<u>H</u>	W
①	2	3	4	_	(5)	6	7

Item	Description							
1	R : Raystar Optronics Inc.							
2	Diaplay	C: Character Type,		T:TAB Type				
	Display	G: Graphic Type		X:COG Type				
3	Display Font :	128 * 64 dot						
4	Serials code :							
		P→TN Positive, Gray		V→FSTN Ne	egative, Blue			
		N→TN Negative,		T→FSTN Ne	egative, Black			
		L→VA Negative		D→FSTN N	egative (Double film)			
		H→ HTN Positive, Gray		F→FSTN Po	ositive			
5	LCD	I→HTN Negative, Black		K→FSC Neg	gative			
		U→HTN Negative, Blue		S→FSC Pos	sitive			
		B→STN Negative, Blue		E→ISTN Ne	gative, Black			
		G→STN Positive, Gray		C→CSTN Negative, Black				
		Y→STN Positive, Yellow	Green	A→ASTN Negative, Black				
		A: Reflective, N.T, 6:00		K: Transflective, W.T,12:00				
	Polarizer	D: Reflective, N.T, 12:00		1 : Transflective, U.T,6:00				
	Type,	G: Reflective, W. T, 6:00	)	4: Transfled	ctive, U.T.12:00			
	Temperature	J: Reflective, W. T, 12:0		C: Transmissive, N.T,6:00				
6	range,	0: Reflective, U. T, 6:00		F: Transmissive, N.T,12:00				
	, <b>.</b>	3: Reflective, U. T, 12:0		I: Transmissive, W. T, 6:00				
	View	B: Transflective, N.T,6:0			ssive, W.T,12:00			
	direction	E: Transflective, N.T.12			ssive, U. T, 6:00			
		H: Transflective, W.T,6:			sive, U.T,12:00			
	1	N→ Without backlight	W→LE	•	H→LED, High light White			
		P→EL, Blue		, Amber	S→LED, Full color			
		T→EL, Green	R→LED		J→DIP LED, Blue			
7	Backlight	D→EL, White		), Orange	K→DIP LED, White			
		M→EL, Yellow Green	B→LED	*	E→DIP LED, Yellow			
		F→CCFL, White		, Dual color	L→DIP LED, Amber			
		Y→LED, Yellow Green	C→LED	, Full color	I→DIP LED, Red			
		G→LED, Green						



## **3.Interface Pin Function**

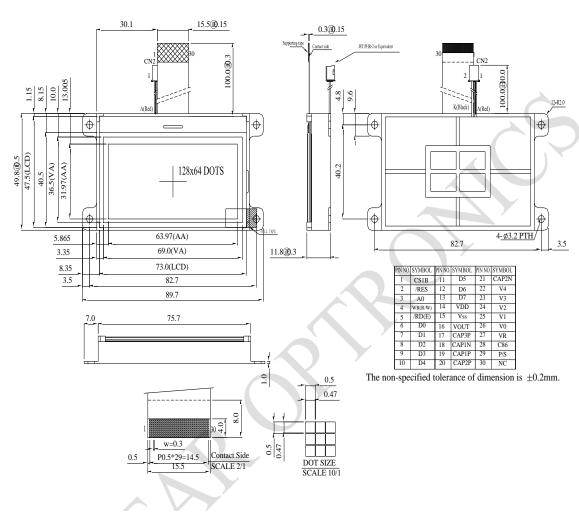
Pin No.	Symbol	I/O	Description
1	/CS1B	I	This is the chip select signal.
2	/RES	I	When RES is set to "L", the setting are initialized.
3	A0	I	This is connect to the least significant bit of the normal MPU address bus, and it determines whether the data bits are data or command.  A0 = "H": Indicates that D0 to D7 are display data.  A0 = "L": Indicates that D0 to D7 are control data.
4	/WR(R/W)	I	<ul> <li>When connected to 8080 series MPU, this pin is treated as the "/WR" signal of the 8080 MPU and is LOW-active.</li> <li>The signals on the data bus are latched at the rising edge of the /WR signal.</li> <li>When connected to 6800 series MPU, this pin is treated as the "R/W" signal of the 6800 MPU and decides the access type:</li> <li>When R/W = "H": Read.</li> <li>When R/W = "L": Write.</li> </ul>
5	/RD(E)		<ul> <li>When connected to 8080 series MPU, this pin is treated as the "/RD" signal of the 8080 MPU and is LOW-active.</li> <li>The data bus is in an output status when this signal is "L".</li> <li>When connected to 6800 series MPU, this pin is treated as the "E" signal of the 6800 MPU and is HIGH-active.</li> <li>This is the enable clock input terminal of the 6800 Series MPU.</li> </ul>
6~13	D0~ D7	I/O	Data bus line
14	VDD	Power Supply	Power supply
15	VSS	Power Supply	Ground
16	VOUT	0	DC/DC voltage converter. Connect a capacitor between this terminal and vss or VDD

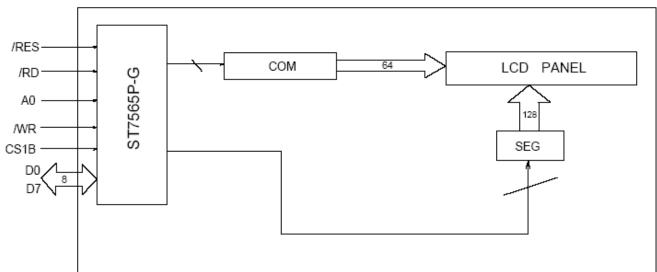


17	CAP3P	0		DC/DC voltage converter. Connect a capacitor between his terminal and the CAP1N terminal.					
18	CAP1N	0	DC/DC	voltage conve	rter. Conn	ect a capa	citor betwee	n	
19	CAP1P	0	DC/DC	voltage conve	rter. Conn	ect a capa	citor betwee	n	
20	CAP2P	0		voltage conve		•	citor betwee	n	
21	CAP2N	0		voltage conve ninal and the 0		•	citor betwee	₽N	
22~26	V4~ V0	Power Supply	This is a drive.	a multi-level po	ower supp	y for the li	quid crystal		
27	VR	I	betweer IRS = "L not used	voltage regulated VSS and V0  The V0 voltage of the V0 to the V0 voltage of the V0 v	through a age regula	resistive v ator interna	roltage divide	er. re	
28	C86	I	C86 = "I	he MPU interfa H": 6800 Serie L": 8080 Serie	s MPU int	erface.			
29	P/S		C86 = "L": 8080 Series MPU interface  This is the parallel data input/serial data input switch terminal.  P/S = "H": Parallel data input.  P/S = "L": Serial data input.  The following applies depending on the P/S status:  P/S Data/Command Data Read/Write Serial Clock  "H" A0 D0 to D7 /RD, /WR X  "L" A0 SI (D7) Write only SCL (D6)  When P/S = "L", D0 to D5 fixed "H".  /RD (E) and /WR (R/W) are fixed to either "H" or "L".  With serial data input, It is impossible read data from RAM					M	
30	NC	-	No conr	nection.					



## 4. Contour Drawing & Block Diagram





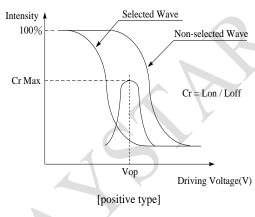


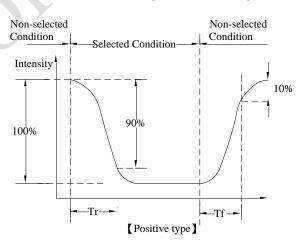
## **5.Optical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	θ	CR <u>≥</u> 2	0	_	30	ψ= 180°
	θ	CR <u>≥</u> 2	0	_	60	ψ= 0°
	θ	CR <u>≥</u> 2	0	_	45	ψ= 90°
	θ	CR <u>≥</u> 2	0	1	45	ψ= 270°
Contrast Ratio	CR	_		5	_	_
Doonongo Timo	T rise	- /		200	300	ms
Response Time	T fall		-	250	350	ms

#### **Definition of Operation Voltage (Vop)**

#### **Definition of Response Time (Tr, Tf)**





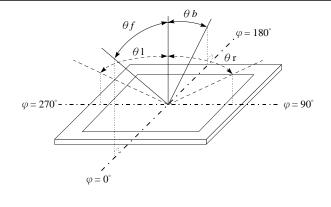
#### **Conditions:**

Operating Voltage : Vop Viewing Angle( $\theta$ ,  $\phi$ ) :  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

### Definition of viewing angle(CR≥2)







# **6.Absolute Maximum Ratings**

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	°C
Storage Temperature	T <sub>ST</sub>	-30	_	+80	ů
Power Supply Voltage	VDD	-0.3	_	3.6	V
Power supply voltage (VDD standard)	V0, VOUT	-0.3	4	14.5	V
Power supply voltage (VDD standard)	V1, V2, V3, V4	-0.3		V0+0.3	V



### 7. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For	V <sub>DD</sub> -V <sub>SS</sub>	_	2.7		3.3	V
Logic	VDD-VSS		2.1		ა.ა	V
		Ta=-20°C	9.5	9.8	10.5	<b>&gt;</b>
Supply Voltage For LCM	Vo-Vss	Ta=25°C	9.2	9.45	9.7	V
		Ta=70°C	8.95	9.2	9.45	V
Input High Volt.	Vih	_	0.8 V <sub>DD</sub>		$V_{DD}$	V
Input Low Volt.	VIL	- (	Vss	_	0.2 V <sub>DD</sub>	V
Output High Volt.	Vон	I <sub>О</sub> = -0.5 mA	0.8 V <sub>DD</sub>	_	V <sub>DD</sub>	V
Output Low Volt.	Vol	I <sub>OUT</sub> =0.5mA	Vss	_	0.2V <sub>DD</sub>	V
Supply Current(No						
include	I <sub>DD</sub>	_	_	0.60	2.0	mA
LED Backlight)						

NOTE 1: 1) Duty ratio=1/65, Bias=1/9

2) Measured in Dots ON-state

NOTE 2: Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance



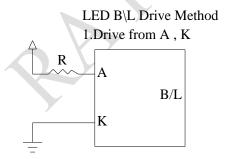
## 8.Backlight Information

#### **Specification**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	61.2	72	100	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	4
Reverse Voltage	VR	_	_	5	V	-
Luminance (Without LCD)	IV	600	800	_	CD/M <sup>2</sup>	ILED=72mA
Move Length	х	0.27	0.3	0.33	V	ILED=72mA
Wave Length	Y	0.26	0.29	0.32	<b>Y</b>	ILED-72IIIA
LED Life Time	_	_	50000	) >	Hr.	ILED≦72 mA 25°C,50-60%RH
Color	White				<u> </u>	<u> </u>

Note: The LED of B/L is drive by current only; driving voltage is only for reference To make driving current in safety area (waste current between minimum and maximum).

Note1:50K hours is only an estimate for reference.





## 9. Reliability

	Environmental Test							
Test Item	Content of Test	Test Condition	Note					
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2					
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2					
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs						
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1					
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2					
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles						
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3					
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times						

Content of Reliability Test (Wide temperature, -20°C~70°C)

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



# 10.Inspection specification

NO	Item	Criterion			AQL		
		1.1 Missing vertical, horizontal segment, segment contrast					
		defect.					
		1.2 Missing character, dot or icon.					
		1.3 Display malfunction.					
01	Electrical Testing	1.4 No function or no display.					
	resung	1.5 Current cons	1.5 Current consumption exceeds product specifications.				
		1.6 LCD viewing	angle def	fect.			
		1.7 Mixed produ	ct types.				
		1.8 Contrast def	ect.				
	Black or white	2.1 White and b	lack spots	on display $\leq$ 0.25	mm, no more than		
02	spots on LCD	three white c	r black sp	ots present.	Y	2.5	
02	(display only)	2.2 Densely spaced: No more than two spots or lines within					
	3mm				1		
		3.1 Round type : As following drawing					
		Ф=( x + y ) /	2	SIZE	Acceptable Q TY		
				Ф≦0.10	Accept no dense		
				0.10<Φ≦0.20	2		
				0.20<Φ≦0.25	1	2.5	
		1		0.25<Ф	0	2.0	
	LCD black	X	1				
	spots, white	<b>→</b>	<u>¥</u> .				
03	spots,	• •	<b>x</b> Y				
	contamination		Te e				
	(non-display)	3.2 Line type : (/	As followin	g drawing)			
		0.00	Length	Width	Acceptable Q TY		
1		→ L <del>w</del>		W≦0.02	Accept no dense		
			L≦3.0	0.02 <w≦0.03< td=""><td>2</td><td>2.5</td></w≦0.03<>	2	2.5	
	<i>&gt;</i>	87E.0	L≦2.5	0.03 <w≦0.05< td=""><td>2</td><td></td></w≦0.05<>	2		
	-			0.05 < W	As round type		





04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in	$\Phi \le 0.20$ asy $0.20 < \Phi \le 0.50$	Acceptable Q TY Accept no dense	2.5
0.4	Polarizer		0.20<Φ≦0.50	3	2.5
04	bubbles	•		2	
		specify direction.	1.00<Ф	0	
			Total Q TY	3	





NO	Item	Criterion A			AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
		Symbols Define:			
				hickness	
			Glass thickness a: LCD	side length	
		L: Electrode pad length	:		
		C.4. Company place ship	_		
		6.1 General glass chip	: face and crack between	nanole:	
		0.1.1 Chip on paner sur	Y	parieis.	
			N. C.		
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing	x≦1/8a	
06	Chipped		area		2.5
	glass	1/2t < z≦2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or more 6.1.2 Corner crack:	chips, x is total length of	y	
		z: Chip thickness	y: Chip width	x: Chip length	
8		Z≦1/2t	Not over viewing area	x≦1/8a	
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or more	chips, x is the total leng	th of each chip.	



NO	Item	Criterion	AQL		
		Symbols:			
		x: Chip length y: Chip width z: Chip thickness			
		k: Seal width t: Glass thickness a: LCD side length			
		L: Electrode pad length 6.2 Protrusion over terminal:			
		6.2.1 Chip on electrode pad :			
		6.2.1 Chip on electrode pad .			
		137			
		V X			
		y: Chip width x: Chip length z: Chip thickness			
		$y \le 0.5$ mm $x \le 1/8$ a $0 < z \le t$			
		6.2.2 Non-conductive portion:			
		, T			
	Class				
06	Glass crack		2.5		
	Clack	12			
		X			
		Ohio di Ula di Ohio Langula di Ohio Uhio di Ingara			
		y: Chip width x: Chip length z: Chip thickness			
		$y \le L$ $x \le 1/8a$ $0 < z \le t$			
		⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO			
	4	must remain and be inspected according to electrode terminal			
		specifications.			
		⊙ If the product will be heat sealed by the customer, the alignment			
		mark not be damaged.			
		6.2.3 Substrate protuberance and internal crack.			
		y: width x: length			
		$y \le 1/3L$ $x \le a$			
		у			
		380			



NO	Item	Criterion	AQL	
07	Cracked glass	The LCD with extensive crack is not acceptable.		
		8.1 Illumination source flickers when lit.	0.65	
08	Backlight elements	8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.	2.5	
		8.3 Backlight doesn't light or color wrong.	0.65	
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.		
		9.2 Bezel must comply with job specifications.	0.65	
		<ul><li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li><li>10.2 COB seal surface may not have pinholes through to the</li></ul>	2.5	
		IC.	2.5	
		<ul><li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li><li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li></ul>		
		10.5 No oxidation or contamination PCB terminals.	2.5	
10	PCB · COB	10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.		
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65	
	4	10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5	
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5	
Y		X * Y<=2mm2		
7		11.1 No un-melted solder paste may be present on the PCB.	2.5	
		11.2 No cold solder joints, missing solder connections,	2.5	
11	Soldering	oxidation or icicle.		
		11.3 No residue or solder balls on PCB.	2.5	
		11.4 No short circuits in components on PCB.	0.65	



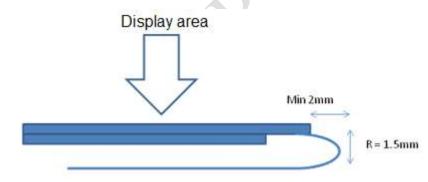


NO	Item	Criterion	AQL
NO	Item	Criterion  12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.  12.2 No cracks on interface pin (OLB) of TCP.  12.3 No contamination, solder residue or solder balls on product.  12.4 The IC on the TCP may not be damaged, circuits.  12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to	2.5 0.65 2.5 2.5 2.5
12	General appearance	<ul> <li>sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.</li> <li>12.7 Sealant on top of the ITO circuit has not hardened.</li> <li>12.8 Pin type must match type in specification sheet.</li> <li>12.9 LCD pin loose or missing pins.</li> <li>12.10 Product packaging must the same as specified on packaging specification sheet.</li> <li>12.11 Product dimension and structure must conform to product specification sheet.</li> <li>12.12 Visual defect outside of VA is not considered to be rejection.</li> </ul>	2.5 2.5 0.65 0.65 0.65



#### 11.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11) The limitation of FPC bending





### 12. Material List of Components for RoHs

1. RAYSTAR Optronics. Inc. hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2.Process for RoHS requirement: (only for RoHS inspection)
  - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
  - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.



## 13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



Page: 1

	LCM Sample	Estimate Feedback Sheet			
Module Number :					
1 · Panel Specification :					
1. Panel Type:	□ Pass	□ NG ,			
2. View Direction:	□ Pass	□ NG ,			
3. Numbers of Dots:	□ Pass	□ NG ,			
4. View Area:	□ Pass	□ NG ,			
5. Active Area:	□ Pass	□ NG ,			
6.Operating Temperature:	□ Pass	□ NG ,			
7.Storage Temperature:	□ Pass	□ NG ,			
8.Others:					
2 · Mechanical Specification :					
1. PCB Size:	□ Pass	□ NG ,			
2.Frame Size:	□ Pass	□ NG ,			
3.Materal of Frame:	□ Pass	□ NG ,			
4.Connector Position:	□ Pass	□ NG ,			
5.Fix Hole Position:	□ Pass	□ NG ,			
6.Backlight Position:	□ Pass	□ NG ,			
7. Thickness of PCB:	□ Pass	□ NG ,			
8. Height of Frame to PCB:	□ Pass	□ NG ,			
9.Height of Module:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
3 · Relative Hole Size :	. 77				
1.Pitch of Connector:	□ Pass	□ NG ,			
2.Hole size of Connector:	□ Pass	□ NG ,			
3.Mounting Hole size:	□ Pass	□ NG ,			
4.Mounting Hole Type:	□ Pass	□ NG ,			
5.Others:	□ Pass	□ NG ,			
4 · Backlight Specification :					
1.B/L Type:	□ Pass	□ NG ,			
2.B/L Color:	□ Pass	□ NG ,			
3.B/L Driving Voltage (Reference for LED Type) : □ Pass □ NG ,					
4.B/L Driving Current:	□ Pass	□ NG ,			
5.Brightness of B/L:	□ Pass	□ NG ,			
6.B/L Solder Method:	□ Pass	□ NG ,			
7.Others:	□ Pass	□ NG ,			

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Module Number :				
5 · Electronic Characteristics of Module :				
1.Input Voltage:	□ Pass	□ NG ,		
2.Supply Current:	□ Pass	□ NG ,		
3.Driving Voltage for LCD:	□ Pass	□ NG ,		
4.Contrast for LCD:	□ Pass	□ NG ,		
5.B/L Driving Method:	□ Pass	□ NG ,		
6.Negative Voltage Output:	□ Pass	□ NG ,		
7.Interface Function:	□ Pass	□ NG ,		
8.LCD Uniformity:	□ Pass	□ NG ,		
9.ESD test:	□ Pass	□ NG ,		
10.Others:	□ Pass	□ NG ,		
Customer Signature :		Date: / /		